



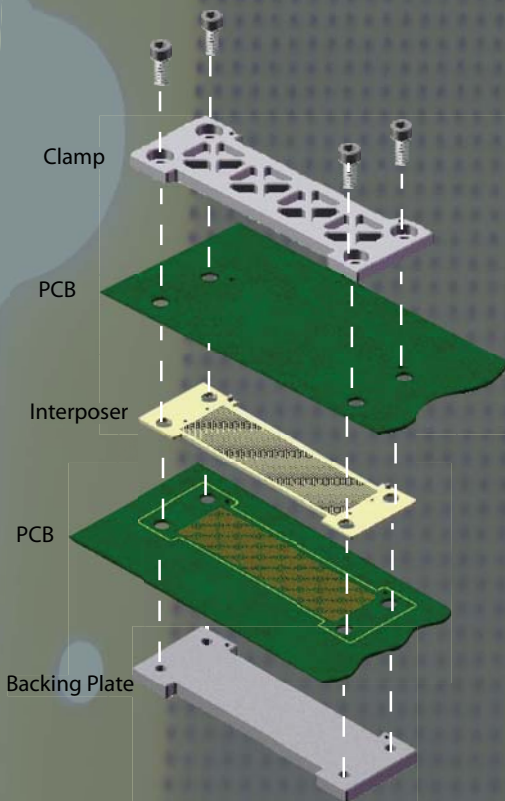
HIGH CONNECTION DENSITY, INC.

SuperButton® & SuperSpring® Interposers (Board-to-Board Applications)

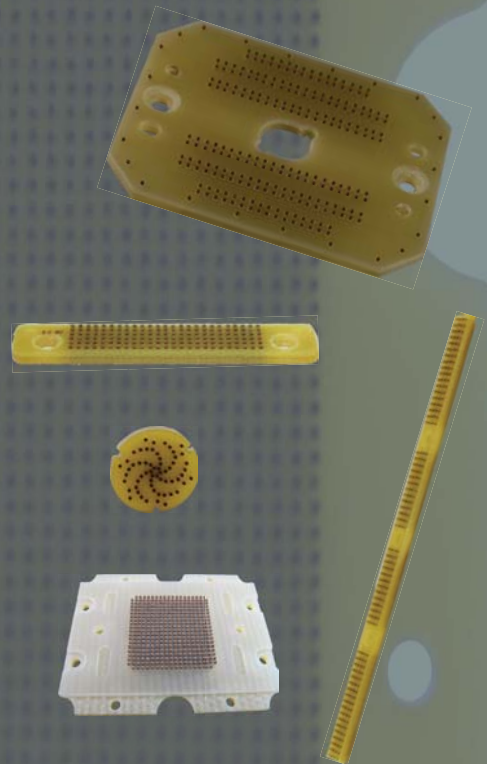
In today's high performance applications, the required data bandwidth transferred between subsystems challenges traditional methods of board-to-board interconnection. Incorporating proprietary *SuperButton®* and *SuperSpring®* technology, HCD interposers have become the technology of choice for low profile, high frequency, high current, and high pin count applications.

HCD interposers fit either standard or non-standard footprints down to 0.5mm pitch. With stacking heights down to 0.8mm, as well as different PCB orientations (right angle, planar and stacked,) our board-to-board connectors are highly reliable at competitive prices.

Board-to-Board Application



Interposer Examples



Features:

- Low Profile (down to 0.8mm)
- High Frequency (Up to 30 GHz @ -1dB)
- Low Contact Resistance (<10m Ω)
- High Pin Count (>5,000)
- In-house Manufacturing
- High Durability
- Accommodates standard, non-standard footprint with varied, asymmetric and irregular pitches
- "Softer" contacts for additional compliance at low force

High Connection Density, Inc.

820A Kifer Road, Sunnyvale, CA 94086

☎ 408-743-9700

☎ 408-743-9701

www.hcdcorp.com

sales@hcdcorp.com

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SuperButton®



SuperSpring®